VOXTECH 3D

MICRO 3D PRINTING

EQUIPMENT / MATERIALS / SERVICES

Precision manufacturing for the smallest features.

START YOUR NEXT PROJECT

(818) 840-6919

info@voxtech3D.com

Upload your parts here >

About



About Us

Xingsheng Precision is based on technology and integrates R&D, production and sales.

It focuses on the research and development and production of high-precision 3D printing equipment and materials, and also provides high-precision parts production services.

Business Scope

Micro-nano 3D Printing Equipment

The independently developed high-precision micro-nano printing equipment features stability, high efficiency, wide material adaptability, and high consistency in batch processing.

Material Research and Development

Our company has an experienced high-precision resin R&D team, offering diversified materials (biocompatible, high-strength, high-toughness, elastomeric, etc.), meeting diverse application needs and providing custom material development.

Micro-nano parts processing Services

We offer fast and low-cost micro-nano parts processing services without mold opening, with the fastest delivery within 3 days.

Model Comparison



	P102 Plus	P110 Plus	P215 Plus	P135
Optical Accuracy	2μm	10μm	15μm	35μm
Build Size	60 x 60 x 50 (mm)	115×128x65 (mm)	84 x 63 x 70 (mm)	67.2 x 37.8 x 150 (mm)
Print layer Thickness	2~50μm	2~50μm	5~50μm	5~50μm
Pixel Count	900M	140M	23.52M	2.07M
Light Source	4K UVLED	4K UVLED	UVLED	UVLED
Printing Materials	Photosensitive Resin, High-Temperature Resistant Resin,Fully Transparent Resin,Flexible Resin,Hydrogel,Zirconia,Alumina and other Ceramic Materials			
Equipment Size	600 x 680 x 690 (mm)	570 x 680 x 750 (mm)	600 x 680 x 690 (mm)	550 x 600 x 700 (mm)
Electrical appliance Requirements	220-240V AC,50-60HZ,1.5KW			
Equipment Weight	70KG	70KG	65KG	50KG

Micro P102 Plus

Micro Nano 3D Printing Equipment



Product Features

Minimum Printable Strut Diameter: 10 μm
Minimum Printable Microfluidic Channel: 20 μm

- Super-large size printing
- Wide range of applications
- Ultra-high precision
- Tiny-level thickness
- Fast printing speed
- Excellent stability

Equipment Parameters

Equipment size : 600mm x 680mm x 690mm
Build size : 60mm x 60mm x 50mm
Optical accuracy : 2μm
Print layer thickness : 2 ~ 50μm
Light source : 4K UVLED
Pixel count (X, Y) : 30000 x 30000
File format: STL
Equipment weight: 70KG
Printing materials: Photosensitive Resin, High-Temperature Resistant Resin, Fully Transparent Resin, Flexible Resin, Zirconia, Alumina and other Ceramic Materials
Electrical appliance requirements : 220-240V AC, 50-60HZ, 1.5KW

Micro P110 Plus

Micro Nano 3D Printing Equipment



Product Features

Minimum Printable Strut Diameter: 40 μm
Minimum Printable Microfluidic Channel: 50 μm

- Super-large size printing
- Wide range of applications
- Ultra-high precision
- Tiny-level thickness
- Fast printing speed
- Excellent stability

Equipment Parameters

Equipment size : 570mm x 680mm x 750mm
Build size : 115mm x 128mm x 65mm
Optical accuracy : 10μm
Print layer thickness : 2 ~ 50μm
Light source : 4K UVLED
Pixel count (X, Y) : 11500 x 12800
File format: STL
Equipment weight: 70KG
Printing materials: Photosensitive Resin, High-Temperature Resistant Resin, Fully Transparent Resin, Flexible Resin, Zirconia, Alumina and other Ceramic Materials
Electrical appliance requirements : 220-240V AC, 50-60HZ, 1.5KW

Micro P215 Plus

Micro Nano 3D Printing Equipment



CE(SGS)

Product Features

Minimum Printable Strut Diameter: 60 μm
Minimum Printable Microfluidic Channel: 100 μm

Large size printing
High precision

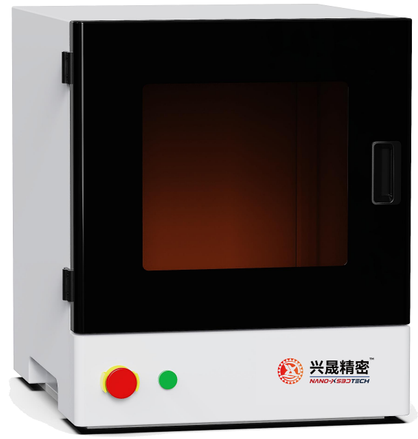
Fast printing speed
Excellent stability

Equipment Parameters

Equipment size : 600mm x 680mm x 690mm
Build size : 84mm x 63mm x 70mm
Optical accuracy : 15μm
Print layer thickness : 5 - 50μm
Light source : UVLED
Pixel count (X, Y) : 5600 x 4200
File format: stl
Equipment weight: 65KG
Printing materials: Photosensitive Resin, High-Temperature Resistant Resin, Fully Transparent Resin, Flexible Resin, Zirconia, Alumina and other Ceramic Materials
Electrical appliance requirements : 220-240V AC, 50-60HZ, 1.5KW

Micro P135

Micro Nano 3D Printing Equipment



CE(SGS)

Product Features

Minimum Printable Strut Diameter: 150 μm
Minimum Printable Microfluidic Channel: 200 μm

Large size printing
High precision

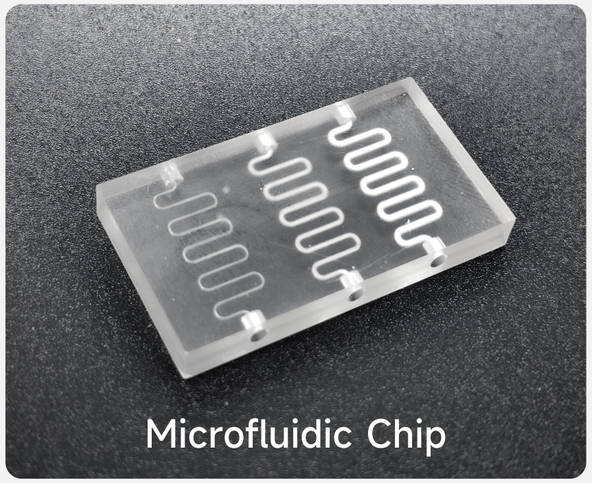
Fast printing speed
Excellent stability

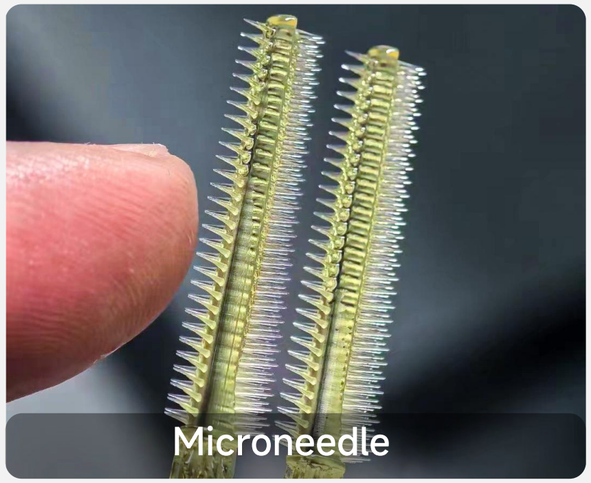
Equipment Parameters

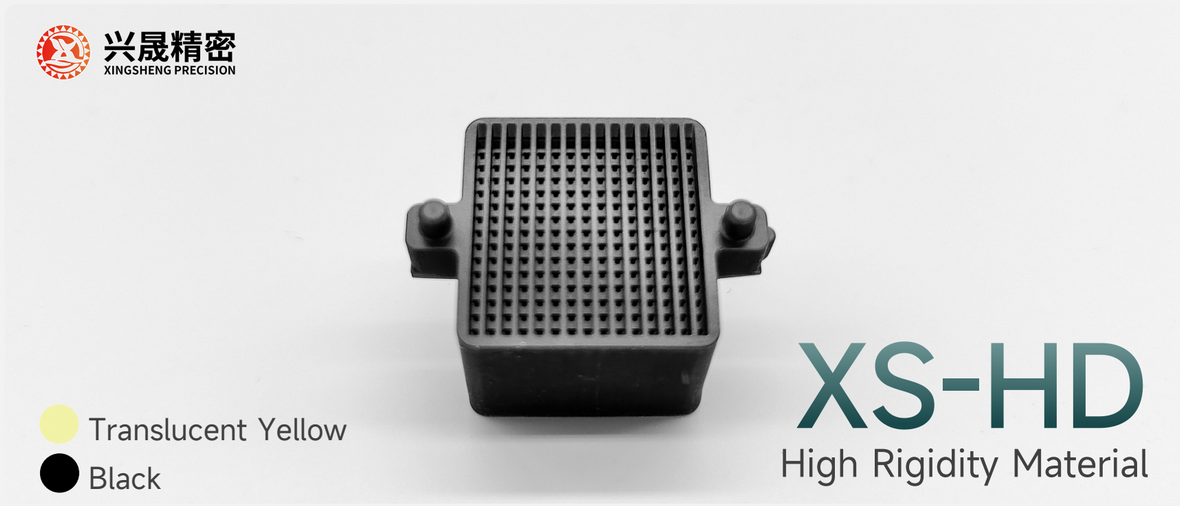
Equipment size : 550mm x 600mm x 700mm
Build size : 67.2mm x 37.8mm x 150mm
Optical accuracy : 35μm
Print layer thickness : 5 - 50μm
Light source : UVLED
Pixel count (X, Y) : 1920 x 1080
File format: STL
Equipment weight: 50KG
Printing materials: Photosensitive Resin, High-Temperature Resistant Resin, Fully Transparent Resin, Flexible Resin, Zirconia, Alumina and other Ceramic Materials
Electrical appliance requirements : 220-240V AC, 50-60HZ, 1.5KW

High Precision Materials

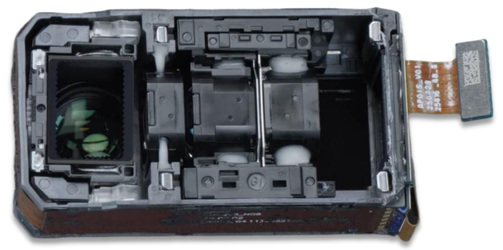






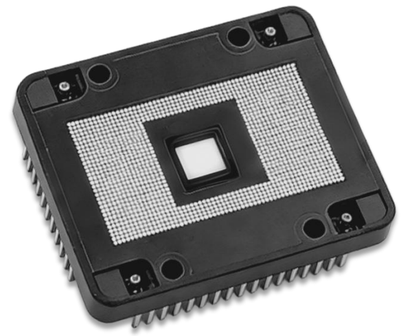


3D-Printed Smartphone Periscope Optical Zoom Module



IC Test Socket

120*100mm



XS-BIO Biocompatible Materials	Tensile strength	Elongation at break	Bending strength
	45/MPa	8/%	50/MPa

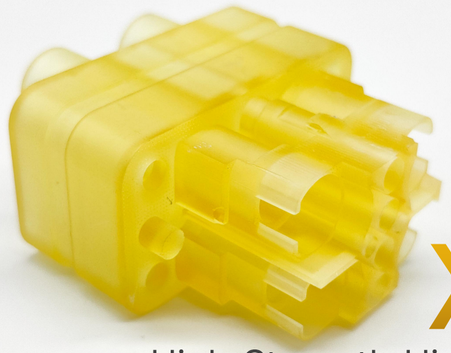
Bending modulus	Heat distortion temperature	Dielectric constant	Dielectric loss	Viscosity	Hardness shore D
1500/MPa	120°C /@0.45MPa	3ε/5GHz	$3.53e^{-2}$ tanε/5GHz	200	80D

XS-HD High Rigidity Material	Tensile strength	Elongation at break	Bending strength
	70/MPa	10/%	100/MPa

Bending modulus	Heat distortion temperature	Dielectric constant	Dielectric loss	Viscosity	Hardness shore D
3800/MPa	80°C /@0.45MPa	3ε/5GHz	$3.53e^{-2}$ tanε/5GHz	100	85D

High Precision Materials

兴晟精密 XINGSHENG PRECISION



Light Yellow
Black

XS-V40

High-Strength High-Toughness Material

兴晟精密 XINGSHENG PRECISION



Light Yellow
Black

XS-HT210

High-Temperature Resistant Material

Micro Gear

Camera Swing Arm

Connector End Housing

RJ45 Connector

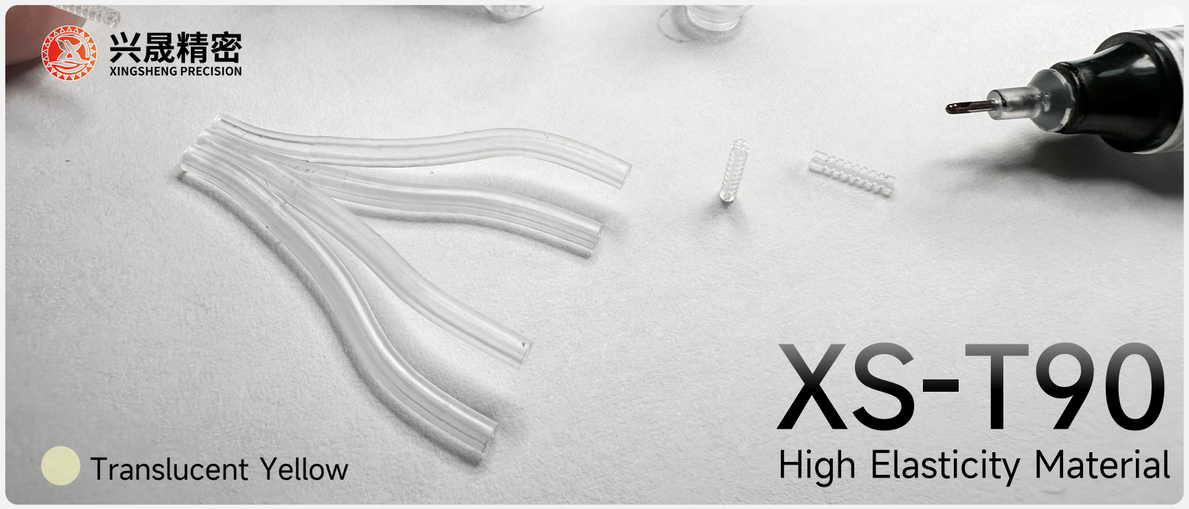
XS-V40 High-Strength High-Toughness Material	Tensile strength	Elongation at break	Bending strength
	42/MPa	34/%	60/MPa

Bending modulus	Heat distortion temperature	Dielectric constant	Dielectric loss	Viscosity	Hardness shore D
1500/MPa	70°C /@0.45MPa	3.1ε/5GHz	$3.12e^{-2}$ tanε/5GHz	800	75D

XS-HT210 High-Temperature Resistant Material	Tensile strength	Elongation at break	Bending strength
	44/MPa	2.5/%	80/MPa

Bending modulus	Heat distortion temperature	Dielectric constant	Dielectric loss	Viscosity	Hardness shore D
3300/MPa	245°C/210°C @0.45MPa/@1.8MPa	2.9ε/5GHz	$3.42e^{-2}$ tanε/5GHz	500	80D

High Precision Materials













XS-T90 High Elasticity Material	Tensile strength 10/MPa	Elongation at break 160/%

Dielectric constant 3ε/5GHz	Dielectric loss $3.12e^{-2}$ tanε/5GHz	Viscosity 600/cps	Hardness shore D 80A

XS-T60 Rigidity Material	Tensile strength 2/MPa	Elongation at break 100/%

Dielectric constant -	Dielectric loss -	Viscosity 1000/cps	Hardness shore D 55A

Compliance & Certifications

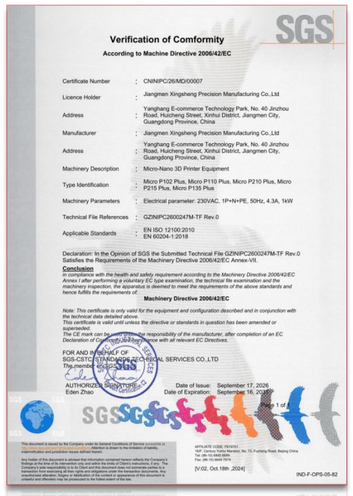


Biocompatibility Test Report

Pass Skin Sensitization
ISO 10993-10 / GB/T 16886.23-2023
Pass Intracutaneous Reactivity
ISO 10993-23 / GB/T 16886.10-2024
Pass Cytotoxicity
ISO 10993-5 / GB/T 16886.5-2017
Pass Acute Systemic Toxicity
ISO 10993-11 / GB/T 16886.11-2021
Pass In Vitro Hemolysis
ISO 10993-4 / GB/T 16886.4-2022



REACH & RoHS
Compliance



SGS Certificate

Cooperative Partner

Universities

Cooperative Enterprise